COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP20815</th>
<th>REV: B</th>
<th>SUN REV: Not In Version Control</th>
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<td>TID #: N/A</td>
<td></td>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED: 7/19/2017 3:12:52 PM</td>
<td>TEXAS INSTRUMENTS</td>
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